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		1	1662	screw and chip and case and	ب ا	2001/02/14 13:48			0
	H	L2	193	il and (clip or pawls or claw or prong)	יע	2001/02/14 11:25			0
		1.3	849	L1 and (clip or pawls or claw or prong or (spring adj connector) or spring)	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 12:08			0
		L4	196	Ll and (clip or pawls or claw or prong or (spring adj connector))	th (t	2001/02/14 14:03			0
BRS		L5	143	Ll and (clip or pawls)	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14			0
BRS		L6	38	L1 and pawls	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14			0
BRS		17	1232	screw and chip and (housing or package)and substrate	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 12:08			0
BRS		87	674	L7 and (clip or finger or pawls o claw or prong or (spring adj connector) or spring)	USPAT; or EPO; Derwent ; IBM TDB	2001/02/14			0
BRS		F-9	144	<pre>(wire adj bond) and (chip near substrate)and (cap or cover or (control adj substrate))</pre>	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 12:54			

L10 L111 L112							S I
		24	L9 and (removable or detachable)	ر د ا	2001/02/14 12:50		0
1 1	H	140	L9 and (case or hous\$ or package or plate)	ע	2001/02/14 12:58	Truncation Overflow. Return string from Server is: 5.2265060	-
	1.2	852	power adj chip	Lt Lt	2001/02/14 12:58		0
<u> </u>	L13	1	L12 and (control adj substrate)	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14		0
H	L14	3144	control adj substrate	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14 13:02		0
<u> </u>	L15	16	L14 and (wire adj bond)	4	2001/02/14		0
<u>н</u>	L16	861	257/718.ccls.	נו	2001/02/14 13:06		0
1	L17	162	257/500.ccls.	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 13:06		0
H	118	0	L17 and screw	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14		0

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USPAT; EPO; JPO; Derwent ; IBM TDB
USPAT; EPO; L26 and chip and (wire adj bond) Derwent ; IBM TDB

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BRS L30 75 257/688.ccls. and chip	75 257/688.ccls. and	257/688.ccls. and	and		th ch	2001/02/14 13:41			0
BRS L31 307 257/696.ccls. and chip	307 257/696.ccls. and	257/696.ccls. and	and		T.	2001/02/14 13:47			0
BRS L32 367 substrate and (removable or detachable)	screw and chip substrate and (detachable)	screw and chip substrate and (detachable)			ا در	2001/02/14 13:56			0
BRS L33 8163 (removable or detachable)	8163		(case or housing or packade) (removable or detachable)	near	ע	2001/02/14 13:58			0
BRS L34 1 chip)	Н		on adj board adj (semiconduct chip)		USPAT; EPO; or JPO; Derwent ; IBM TDB	2001/02/14 13:59			0
(clip or pawls or claw or prong (spring adj connector)) near (spring adj connector)) near (electrodes or terminal or lead)	(clip or pawls or claw (spring adj connector))	(clip or pawls or claw (spring adj connector))	(clip or pawls or claw or pro (spring adj connector)) near electrodes or terminal or lea	ng or (d)		2001/02/14 14:06			0
BRS L36 8 L35 and (wire adj bond)	. α		L35 and (wire adj bond)		USPAT; EPO; JPO; Derwent ; IBM	USPAT; EPO; JPO; Derwent 14:07 ; IBM			0

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BRS L37	152	L35 and chip	USPAT; EPO; JPO; Derwent ; IBM TDB	USPAT; EPO; JPO; 2001/02/14 Derwent 14:08 ; IBM TDB			0

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BRS 0 27/727.ccls. and (on adj board) USRM7; EPO; JFOP Derwent 2001/02/13 USRM7; EPO; JFOP JFOP DERWENT 201/02/13 USRM7; EPO; JFOP JFOP DERWENT 201/02/13 USRM7; EPO; JFOP DERWENT 201/02/13 USRM7; EFOP JFOP DERWENT 201/02/13 US	9	BRS	554	257/727.ccls.	JPO; Derwent;			
BRS 0 257/727.ccls. and (control ad) substrate) USBATH FERO, JPO; Derwent; LBM TOB CONTO2/131	7	BRS	0	.ccls. and (on adj	JPO; Derwent;	•		
BRS 0 297/727.ccls. and (control adj substrate) USBAT; EPO; JPO; Derwent; DOUGL CONTOL CON	ω	BRS	0	and (ocntrol adj	JPO; Derwent;			
BRS 137 257/27.ccls. and (IGBT or Mosfet or mos or leght). Bryns bowerl) USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and substrate or leght; EPO; JPO; Derwent; Double of 257/727.ccls. and 257/735.ccls. USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and substrate USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and substrate USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and substrate USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and substrate USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and substrate USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and substrate USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and substrate USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USFATT EPO; JPO; Derwent; Double of 257/727.ccls. and chip and case USF	0	BRS	0	and (control adj su	EPO; JPO;	18:2		
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BRS 0 251/72.cc1s. and 251/735.cc1s. USPAT; EPO; JPO; Derwent; Derwent Dispanded Services USPAT; EPO; JPO; Derwent Dispanded Services USPAT; EPO; JPO; Derwent Dispanded Services MRM TDB CO1/02/13 BRS 149 251/727.cc1s. and chip and substrate USPAT; EPO; JPO; Derwent; Dispanded Services USPAT; EPO; JPO; Derwent; Dispanded Services USPAT; EPO; JPO; Derwent; Dispanded Services 201/02/13 BRS 12 251/727.cc1s. and chip and substrate USPAT; EPO; JPO; Derwent; Dispanded Services USPAT; EPO; JPO; Derwent; Dispanded Services 201/02/13 BRS 139 251/727.cc1s. and chip and case USPAT; EPO; JPO; Derwent; Dispanded Services 201/02/13 BRS 1039 251/723.cc1s. and chip and case USPAT; EPO; JPO; Derwent; Dispanded Services 201/02/13 BRS 50 251/723.cc1s. and chip and case USPAT; EPO; JPO; Derwent; Dispanded Services USPAT; EPO; JPO; Derwent; Dispanded Services 201/02/13 BRS 50 251/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; Dispanded Services USPAT; EPO; JPO; Derwent; Dispanded Services USPAT; EPO; JPO; Derwent; Dispanded Services BRS 50 251/724.cc1s. and chip and power USPAT; EPO; JPO; Derwent; Dispand	1	BRS	54	and (IGBT or MOsfet or mos o	EPO; JPO; B	i		
BRS 2 257/727.ccls. and 257/735.ccls. IBRATIC EPO; JPO; Derwent; DOU/02/13 COU/02/13 BRS 4.9 257/727.ccls. and chip and substrate IBRATIS EPO; JPO; Derwent; DOU/02/13 201/02/13 BRS 2.57/727.ccls. and chip and substrate IBRATIS EPO; JPO; Derwent; DOU/02/13 201/02/13 BRS 2.57/727.ccls. and chip and substrate IBRATIS EPO; JPO; Derwent; DOU/02/13 201/02/13 BRS 1.0 2.57/727.ccls. and chip and substrate IBRATIS EPO; JPO; Derwent; DOU/02/13 201/02/13 BRS 1.063 2.57/727.ccls. IBRATIS EPO; JPO; Derwent; DOU/02/13 201/02/13 BRS 6.0 2.57/723.ccls. IBRATIS EPO; JPO; Derwent; DOU/02/13 201/02/13 BRS 6.0 2.57/723.ccls. and chip and case IBR TDB IBR TDB 201/02/13 BRS 5.0 2.57/724.ccls. and chip and power IBR TDB IBR TDB 201/02/13 BRS 5.1 2.57/724.ccls. and chip and power IBR TDB 1.BR TDB 201/02/13 BRS 6.0 2.57/691.ccls. and chip and power IBR TDB 1.BR TDB 201/02/13 BRS 6.0 2.57/734	12		0	257/72.ccls. and 257/735.ccls.	EPO; JPO;			
BRS 149 251/727.ccls. and chip USPAT; EPO; JPO; Derwent; DIPO, DERW	13		2	and	EPO; JPO;			
BRS 33 257/727.cc1s. and chip and substrate USPMT; EPO; JPO; Derwent; DSPMT;	14	\top	149	and.	USPAT; EPO; JPO; Derwent; IBM TDB			
BRS 12 257/727.cc1s. and spring USPAT; EPO; JPO; Derwent; Derwent 201/02/13 BRS 319 257/735.cc1s. USPAT; EPO; JPO; Derwent; Derwent 2001/02/13 BRS 1063 257/724.cc1s. USPAT; EPO; JPO; Derwent; Derwent 2001/02/13 BRS 1089 257/723.cc1s. USPAT; EPO; JPO; Derwent; Derwent 2001/02/13 BRS 667 257/723.cc1s. and chip and case USPAT; EPO; JPO; Derwent; Derwent; Derwent 2001/02/13 BRS 570 257/724.cc1s. and chip and case USPAT; EPO; JPO; Derwent; Derwe	15	\neg	83	and chip and	USPAT; EPO; JPO; Derwent; IBM TDB			
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BRS 633 257/691.ccls. USPAT; EPO; JPO; Derwent; 2001/02/13 BRS 409 257/707.ccls. IBM TDB 2001/02/13 BRS 737 257/734.ccls. IEM TDB 2001/02/14	25		0	257/691.ccls	JPO;	2001/02/13		
BRS 409 257/707.ccls. IBM TDB 2001/02/13 BRS 737 257/734.ccls. 1EM TDB 2001/02/14	26		633	257/691.ccls.	JPO;	2001/02/13		
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	IS&R	L1	0	("chip and pawl").PN.	ப	2001/02/14			0
<u>m</u>	BRS	L2	752	chip and pawl	↓	2001/02/14 18:33			0
Ш	BRS	L3	173	chip and pawl and substrate	1.1	2001/02/14			0
 	BRS	L4	27667	(case or housing or package) and pawl	ا ب	2001/02/14 18:43			0
	BRS	L5	593	L4 and chip	- 0	2001/02/14 18:44		·	0
9	BRS	1.6	1	L2 and (wire adj bond)		2001/02/14 19:01			0
7	BRS	17	152	screw and (wire adj bond)and chip	USPAT; . EPO; JPO; Derwent ; IBM TDB	2001/02/14			0
8	BRS	L8	11829	screw and chip	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 19:05			0
6	BRS	L9	36	screw and chip and (control near(substrate or (ciruit adj board)))	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 19:18			0
10	BRS	110			USPAT	2001/02/14 19:10			0
11	BRS	L11	1		USPAT	2001/02/14 19:10			<u> </u>

Page 1 (JMitchell2, 02/14/2001, EAST Version: 1.01.0015)

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	BRS	112	1		USPAT	2001/02/14 19:10			0
, ,,,,	BRS	L13	1			2001/02/14 19:11			0
	BRS	1.14	5244	power and chip and screw	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14 19:18			0
	BRS	115	54	L14 and (screw near (case or wall or board))	- 1	2001/02/14			0
16	BRS	L17	320	L16 and chip	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14 19:55			О
	BRS	L18	м	L17 and (wire adj bond)	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14			0
. – – – – – – – – – – – – – – – – – – –	BRS	L19	34	L17 and (screw or pawl)	USPAT; EPO; JPO; Derwent ; IBM	2001/02/14 20:00			0
19	BRS	L20	109	Igbt and screw	USPAT; EPO; JPO; Derwent ; IBM TDB	2001/02/14 20:00			0